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## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



# MS2421

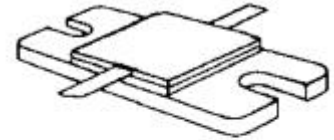
## RF & MICROWAVE TRANSISTORS AVIONICS APPLICATIONS

### Features

- DESIGNED FOR HIGH POWER PULSED IFF, DME, AND TACAN APPLICATIONS
- 350 W (typ.) IFF 1030 – 1090 MHz
- 300 W (min.) DME 1025 – 1150 MHz
- 290 W (typ.) TACAN 960 – 1215 MHz
- 960 – 1215 MHz
- GOLD METALLIZATION
- $P_{OUT} = 300W$  MINIMUM
- $G_p = 6.3$  dB MINIMUM
- INFINITE VSWR CAPABILITY @ RATED CONDITIONS
- EMITTER BALLASTED
- COMMON BASE

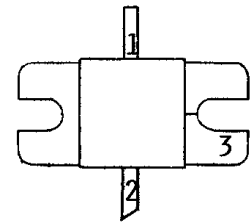
### DESCRIPTION:

The MS2421 is a gold metallized silicon, NPN power transistor designed for applications requiring high peak power and low duty cycles such as IFF, DME, and TACAN. The MS2421 is designed with internal input/output matching resulting in improved broadband performance and low thermal resistance.



.400 x .400 2LFL (M103)  
epoxy sealed

### PIN CONNECTION



1 emitter  
2 collector

3 base

### ABSOLUTE MAXIMUM RATINGS ( $T_{case} = 25^{\circ}C$ )

Symbol	Parameter	Value	Unit
$P_{DISS}$	Power Dissipation	875	W
$V_{CES}$	Collector-Emitter Voltage	65	V
$V_{CBO}$	Collector-Base Voltage	65	V
$V_{EBO}$	Emitter-Base Voltage	3.5	V
$T_J$	Junction Temperature	200	$^{\circ}C$
$I_C$	Device Current	22	A
$T_{STG}$	Storage Temperature	-65 to +200	$^{\circ}C$

### Thermal Data

$R_{TH(J-C)}$	Junction-case Thermal Resistance	0.20	$^{\circ}C/W$
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**ELECTRICAL SPECIFICATIONS (T<sub>case</sub> = 25 °C)**
**STATIC**

Symbol	Test Conditions	Value			Unit
		Min.	Typ.	Max.	
<b>BV<sub>CBO</sub></b>	<b>I<sub>C</sub> = 10 mA      I<sub>E</sub> = 0 mA</b>	<b>65</b>	<b>---</b>	<b>---</b>	<b>V</b>
<b>BV<sub>EBO</sub></b>	<b>I<sub>E</sub> = 5.0 mA      I<sub>C</sub> = 0 mA</b>	<b>3.5</b>	<b>---</b>	<b>---</b>	<b>V</b>
<b>I<sub>CES</sub></b>	<b>V<sub>CE</sub> = 50 V</b>	<b>---</b>	<b>---</b>	<b>25</b>	<b>mA</b>
<b>HFE</b>	<b>V<sub>CE</sub> = 5 V      I<sub>C</sub> = 500mA</b>	<b>10</b>	<b>---</b>	<b>200</b>	<b>mA</b>

**DYNAMIC**

Symbol	Test Conditions	Value			Unit
		Min.	Typ.	Max.	
<b>P<sub>OUT</sub></b>	<b>f =1025 - 1150 MHz    P<sub>IN</sub> = 70W    V<sub>CE</sub> =50V</b>	<b>300</b>	<b>---</b>	<b>---</b>	<b>W</b>
<b>G<sub>P</sub></b>	<b>f =1025 - 1150 MHz    P<sub>IN</sub> = 70W    V<sub>CE</sub> =50V</b>	<b>6.3</b>	<b>---</b>	<b>---</b>	<b>dB</b>
<b>η<sub>C</sub></b>	<b>f =1025 - 1150 MHz    P<sub>IN</sub> = 70W    V<sub>CE</sub> =50V</b>	<b>35</b>	<b>---</b>	<b>---</b>	<b>%</b>
<b>Conditions</b>	<b>Pulse Width = 10 μs    Duty Cycle = 1%</b>				

**IMPEDANCE DATA**

FREQ	Z <sub>IN</sub> (Ω)	Z <sub>CL</sub> (Ω)
<b>960 MHz</b>	<b>2.6 + j6.0</b>	<b>2.5 – j6.0</b>
<b>1090 MHz</b>	<b>7.4 + j4.4</b>	<b>2.4 – j6.2</b>
<b>1215 MHz</b>	<b>4.3 + j1.1</b>	<b>2.5 – j4.9</b>

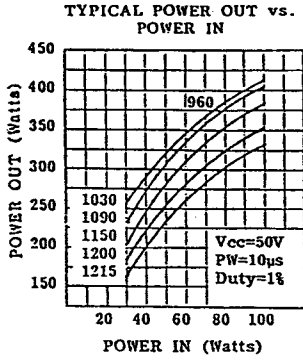
**Pin = 70W    Vce = 50V**



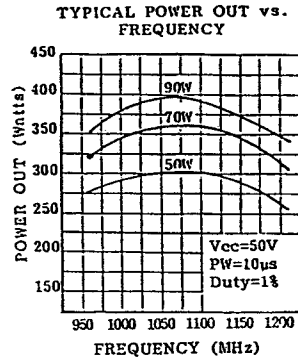
# MS2421

## TYPICAL PERFORMANCE

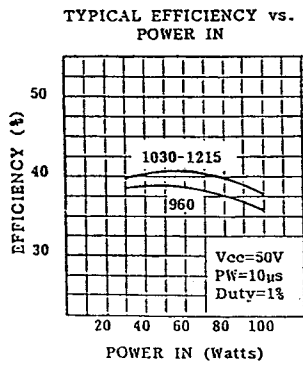
**POWER OUTPUT vs POWER INPUT**



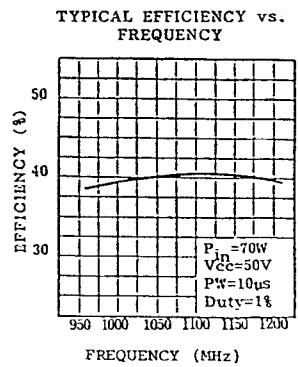
**POWER OUTPUT vs FREQUENCY**



**EFFICIENCY vs POWER INPUT**

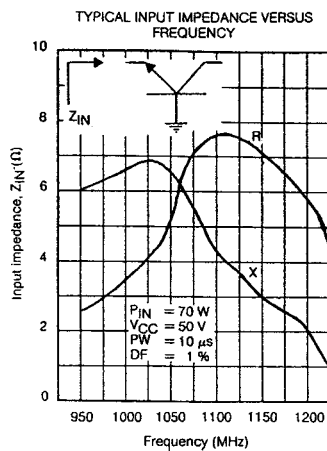


**EFFICIENCY vs FREQUENCY**

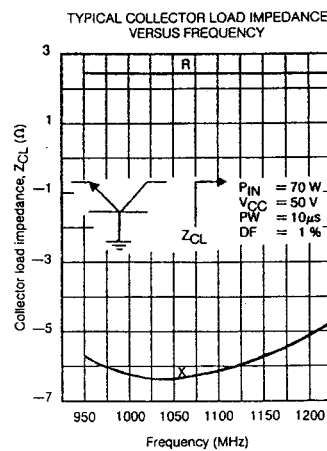


## IMPEDANCE DATA

**TYPICAL INPUT IMPEDANCE**



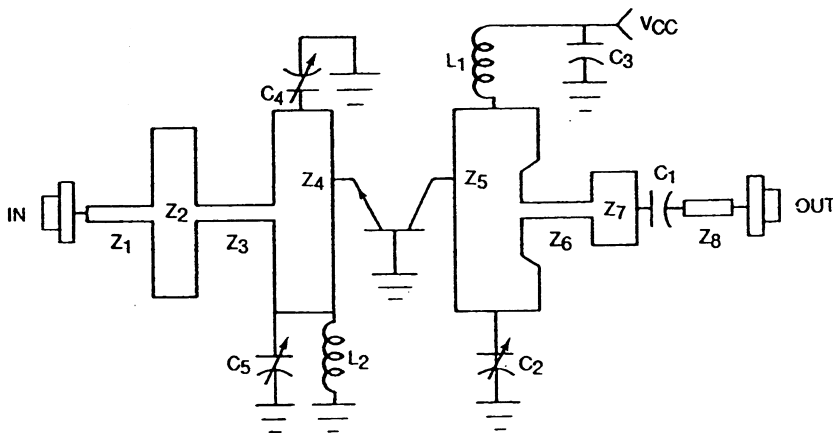
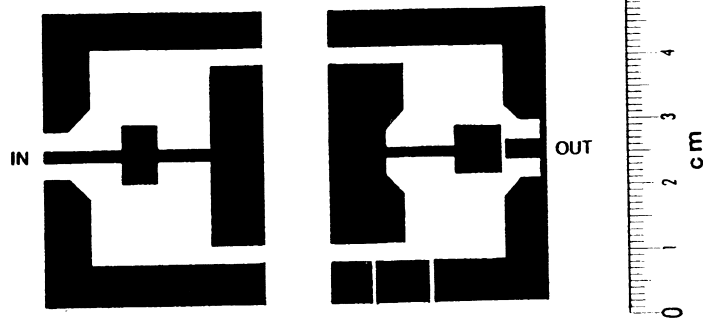
**TYPICAL COLLECTOR LOAD IMPEDANCE**



**MS2421**

TEST CIRCUIT

Teflon Fiberglass  $\epsilon_r = 2.5$  THK .031

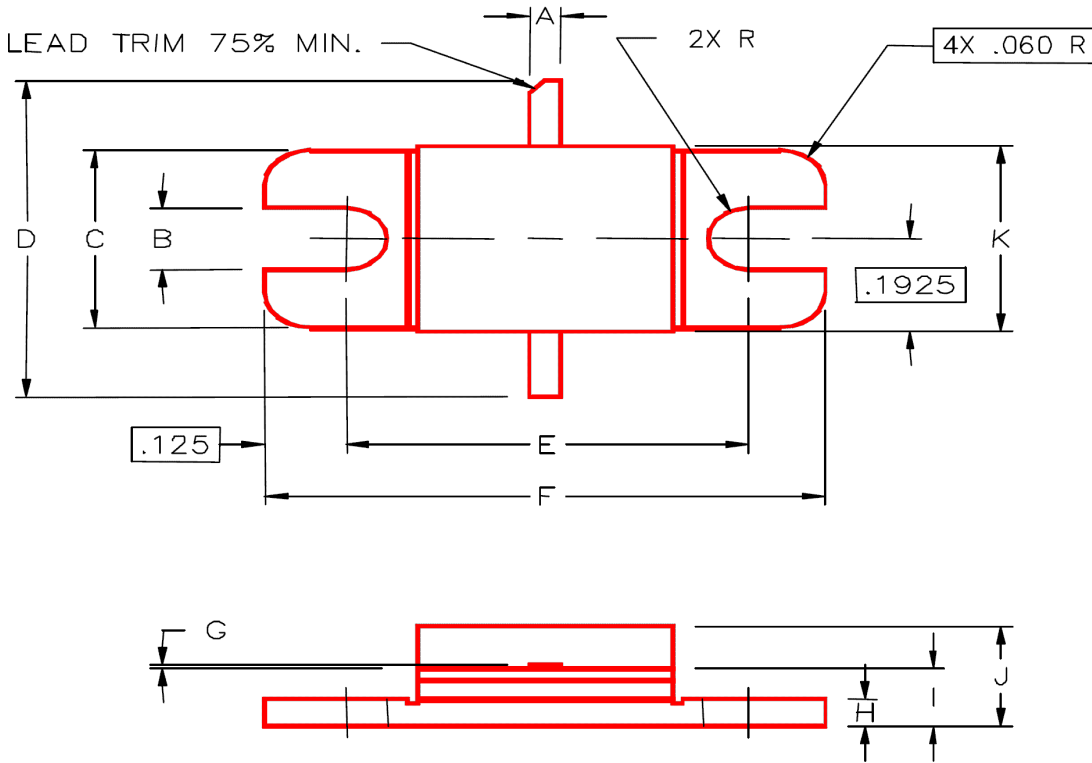


All Dimension are in Inches

C1	: 100pF Chip Capacitor Across .120 Sq. Gap	Z1	: .395 x .083
C2	: .6 - 4.5pF JOHANSON	Z2	: .250 x .340
C3	: 470pF Chip Capacitor Across .120 Sq. Gap	Z3	: .495 x .083
C4, C5	: .35 - 3.5pF	Z4	: .360 x 1.193
L1	: 2 3/4 Turns Diameter 16 Tinned .125 I.D. .215 Long	Z5	: .485 x 1.2
L2	: 2 3/4 Turns Diameter 20 Tinned .090 I.D. .220 Long	Z6	: .520 x .035
		Z7	: .270 x .330
		Z8	: .270 x .110

**PACKAGE MECHANICAL DATA**

**PACKAGE STYLE M103**



	MINIMUM INCHES/MM	MAXIMUM INCHES/MM		MINIMUM INCHES/MM	MAXIMUM INCHES/MM
A	.045/1,14	.055/1,40	I	.110/2,79	.130/3,30
B	.130/3,30		J	.190/4,83	.215/5,46
C	.380/9,65	.390/9,91	K	.390/9,91	.410/10,41
D	.880/22,35	.920/23,37			
E	.645/16,38	.655/16,64			
F	.890/22,61	.910/23,11			
G	.002/0,05	.006/0,15			
H	.055/1,40	.065/1,65			